

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

SYMBOL	PARAMETER	RATING	UNITS
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D^a	Maximum Drain Current-Continuous	$V_{GS} = -10\text{V}$	-4.5
I_{DM}^b	Maximum Drain Current – Pulsed		-16
I_S	Maximum Continuous Drain-Source Diode Forward Current	-1.8	A
P_D^a	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	1.4
		$T_A = 100^\circ\text{C}$	0.3
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}^a$	Thermal Resistance – Junction to Ambient	150	$^\circ\text{C/W}$

Electrical Characteristics ($T_A = 25^\circ\text{C}$, unless otherwise noted)

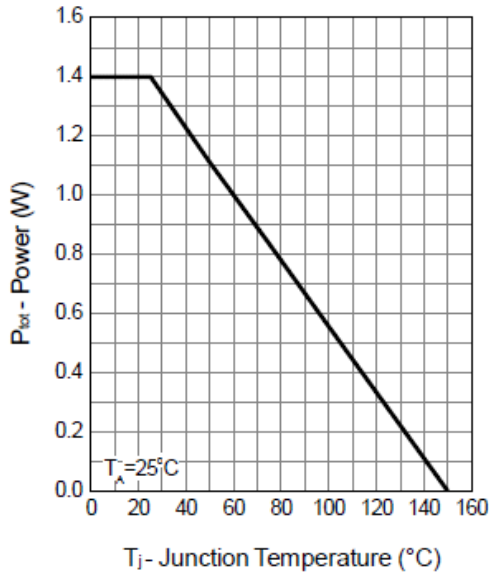
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Static						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_{DS} = -250\mu\text{A}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$			-1	μA
		$T_J = 85^\circ\text{C}$			-30	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = -250\mu\text{A}$	-1	-1.8	-2.5	V
$R_{DS(ON)}^b$	Drain-Source On-state Resistance	$V_{GS} = -10\text{V}, I_{DS} = -4.5\text{A}$		43	52	m Ω
		$V_{GS} = -4.5\text{V}, I_{DS} = -3\text{A}$		60	78	m Ω
V_{SD}^b	Diode Forward Voltage	$I_S = -1.8\text{A}, V_{GS} = 0\text{V}$		-0.8	-1.3	V
Dynamic^c						
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, I_D = -4.5\text{A}, V_{GS} = -10\text{V}$		13	18	nC
Q_{GS}	Gate-Source Charge			2		nC
Q_{GD}	Gate-Drain Charge			3		nC
$T_{D(ON)}$	Turn-on Delay Time	$V_{DD} = -15\text{V}, I_{DS} = -1\text{A}, V_{GEN} = -10\text{V}, R_G = 6\Omega, R_L = 15\Omega$		6	12	nS
T_R	Turn-on Rise Time			11	21	nS
$T_{D(OFF)}$	Turn-off Delay Time			28	51	nS
T_F	Turn-off Fall Time			10	19	nS
T_{RR}	Reverse Recovery Time	$I_{DS} = -4.5\text{A}, dI_{DS}/dt = 100\text{A}/\mu\text{s}$		15		nS
Q_{RR}	Reverse Recovery Charge			6		nC
C_{ISS}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, \text{Frequency} = 1.0\text{MHz}$		800		pF
C_{OSS}	Output Capacitance			130		pF
C_{RSS}	Reverse Transfer Capacitance			75		pF

Notes

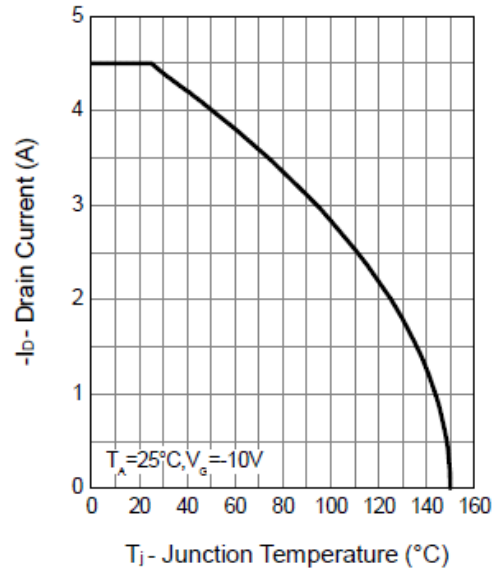
- a: Surface Mounted on FR4 Board, $t \leq 10$ sec.
- b: Pulse test; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- c: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics

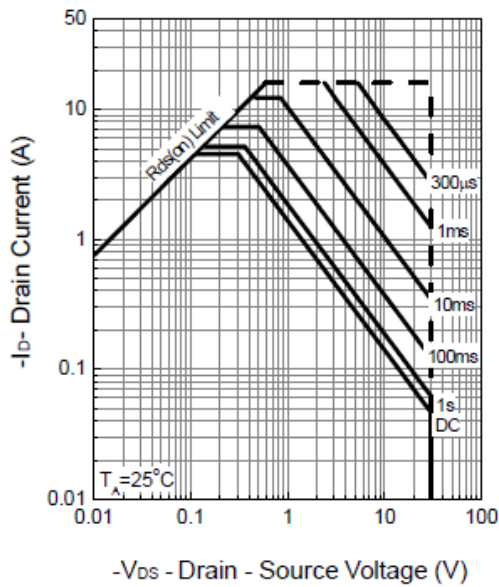
Power Dissipation



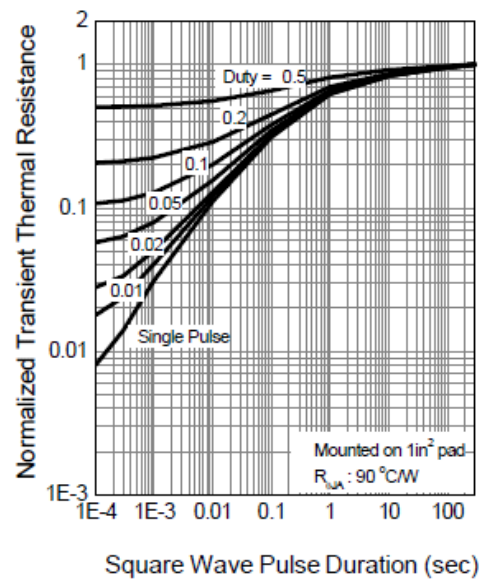
Drain Current



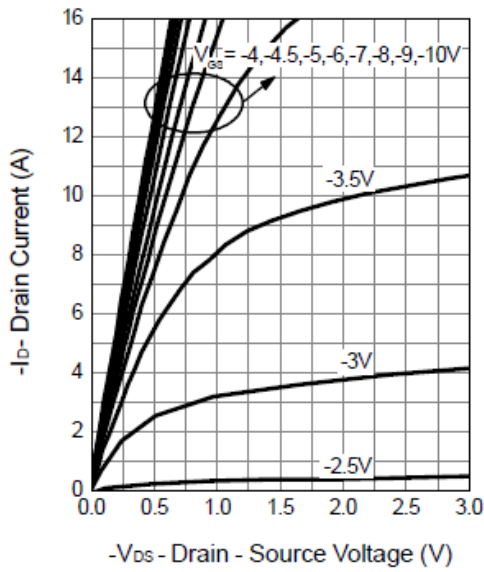
Safe Operation Area



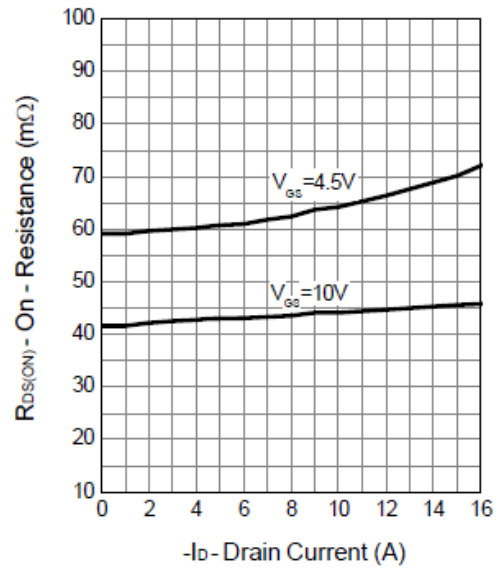
Thermal Transient Impedance



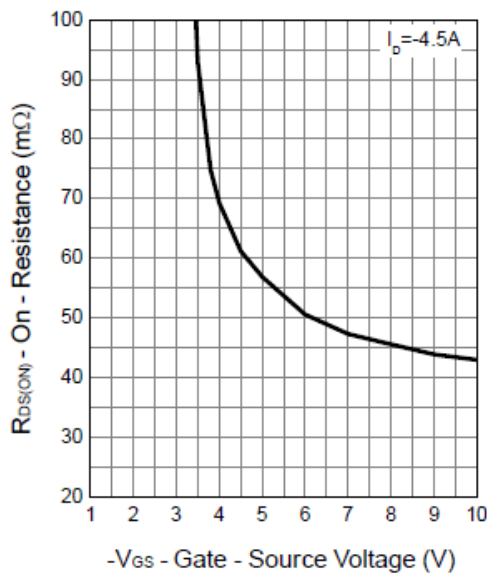
Output Characteristics



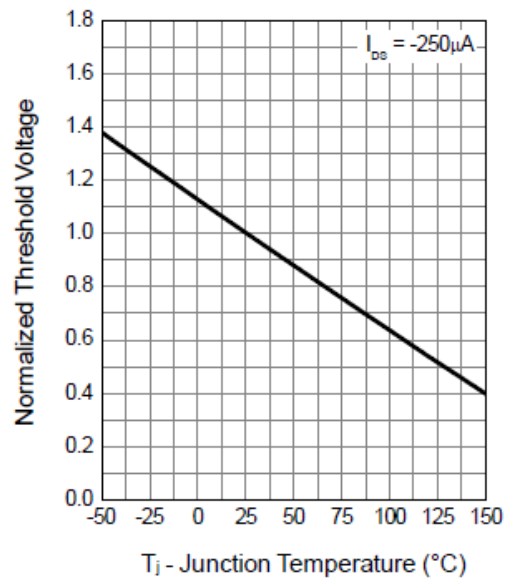
Drain-Source On Resistance



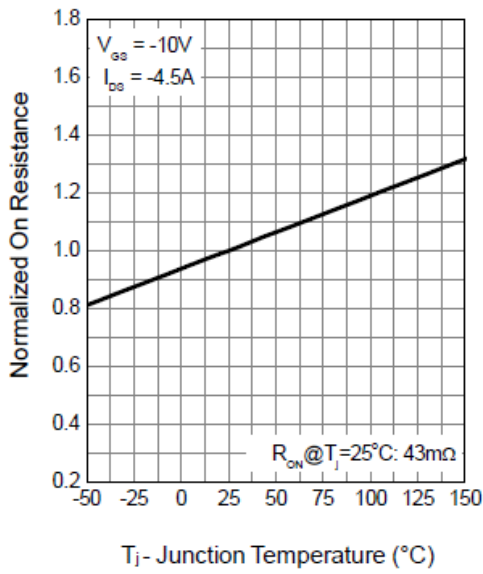
Drain-Source On Resistance



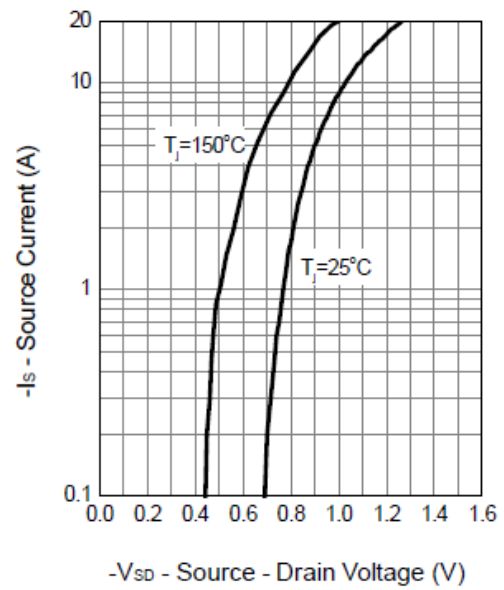
Gate Threshold Voltage



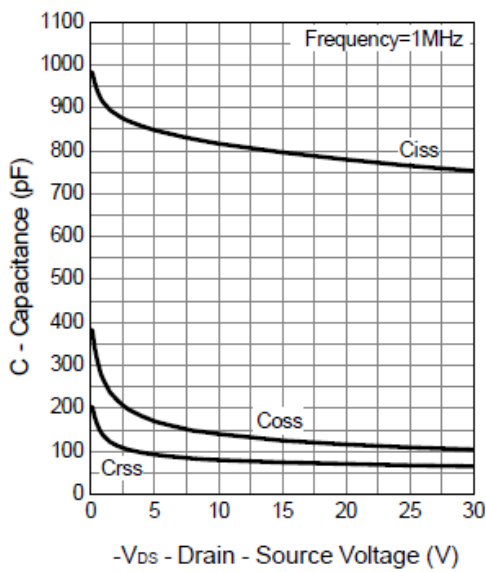
Drain-Source On Resistance



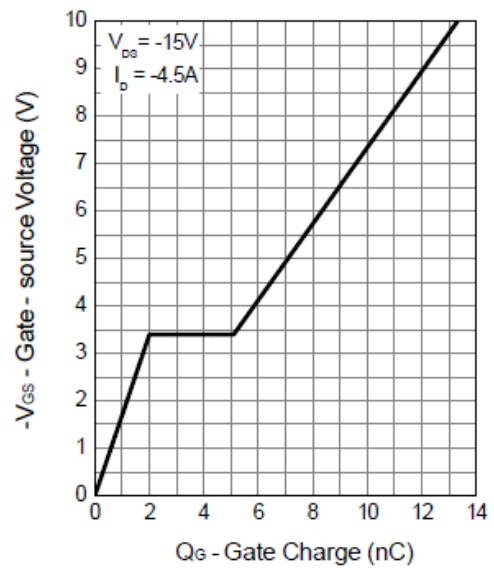
Source-Drain Diode Forward



Capacitance

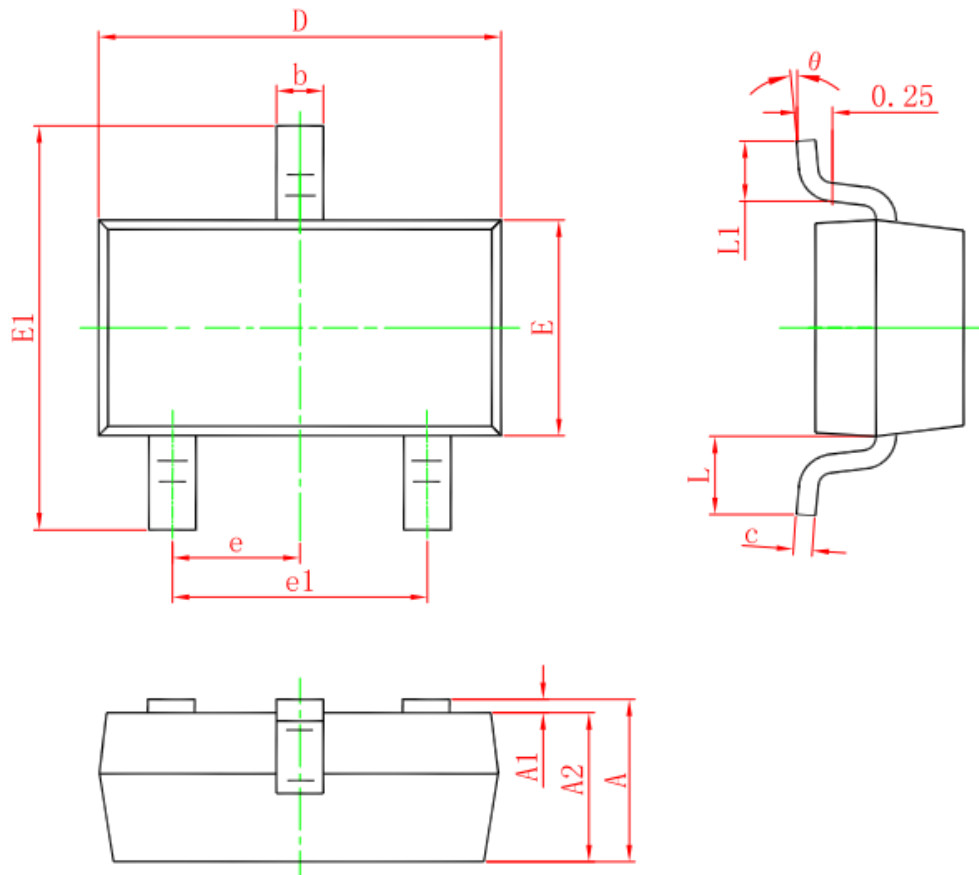


Gate Charge

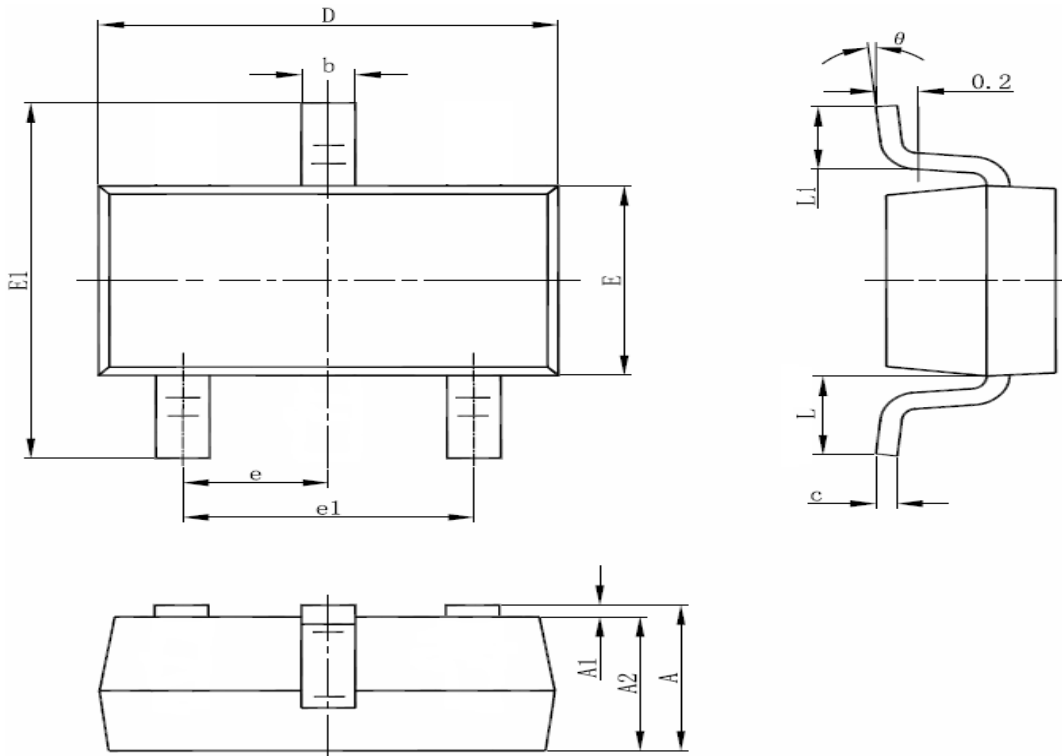


Package Outline Dimensions

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950(TYP.)		0.037(TYP.)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23-3L Package Outline Dimensions


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.700(REF)		0.028(REF)	
L1	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

Subject changes without notice.